Electronic Acknowledgement Receipt FES ID: 1100833 Application Number: 10770711 Confirmation Number: 2278 Predicting defect future effects in integrated circuit technology Title of Invention: development to facilitate semiconductor wafer lot disposition First Named Inventor: Paul J. Steffan Customer Number: 22898 Filer: Mikio Ishimaru/Vickie Ishimaru Filer Authorized By: Mikio Ishimaru Attorney Docket Number: H0897 Receipt Date: 30-JUN-2006 Filing Date: 02-FEB-2004 Time Stamp: 22:27:18 Application Type: Utility International Application Number: Payment information:

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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		H0897_Amendment.pdf	620760	yes	12

no

	maniput 2000.pto.					
	Doc Desc	Start	End			
	Amendment - After Non-Final Rejection	1	1			
	Claims	2	5			
	Applicant Arguments/Remarks Made in an Amendment	6	12			
Warnings:						
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If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.